

PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1
 Stylesheet Version v1.2

EPAS ID: PAT6390085

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
ZOPE BHUSHAN	09/04/2018
KIRAN SHRESTHA	08/21/2018
SHANKAR SWAMINATHAN	09/06/2018
CHIYU ZHU	10/21/2020
HENRI TUOMAS ANTERO JUSSILA	08/22/2018
QI XIE	08/21/2018
RECEIVING PARTY DATA	
Name:	ASM IP HOLDING B.V.
Street Address:	VERSTERKERSTRAAT 8
City:	ALMERE
State/Country:	NETHERLANDS
Postal Code:	1322 AP
PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	16105802
CORRESPONDENCE DATA	
Fax Number:	(602)470-2434
<i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.</i>	
Phone:	6024705707
Email:	michelle.simpson@asm.com
Correspondent Name:	PATRICK LEE
Address Line 1:	3440 E. UNIVERSITY DRIVE
Address Line 4:	PHOENIX, ARIZONA 85034
ATTORNEY DOCKET NUMBER:	PAT-AM-0896-US-NP
NAME OF SUBMITTER:	MICHELLE SYMPSON
SIGNATURE:	/Michelle Simpson/
DATE SIGNED:	11/07/2020
Total Attachments: 7	

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source=PAT-AM-0896-US-NP Assignment Executed#page7.tif

Application Serial No.: 16/105,802

Docket No.: PAT-AM-0896-US-NP

Filing Date: August 20, 2018

Title: METHODS FOR DEPOSITING A MOLYBDENUM METAL FILM OVER A DIELECTRIC SURFACE OF A SUBSTRATE BY A CYCLICAL DEPOSITION PROCESS AND RELATED SEMICONDUCTOR DEVICE STRUCTURES

ASSIGNMENT

WHEREAS, BHUSHAN ZOPE, a citizen of India and a resident of Phoenix, Arizona; KIRAN SHRESTHA, a citizen of Nepal and a resident of Tempe, Arizona; SHANKAR SWAMINATHAN, a citizen of India and a resident of Phoenix, Arizona; CHIYU ZHU, a citizen of China and a resident of Helsinki, Finland; HENRI TUOMAS ANTERO JUSSILA, a citizen of Finland and a resident of Espoo, Finland; and QI XIE, a citizen of Belgium and a resident of Leuven, Belgium;

(collectively, “WE” or “ASSIGNOR”) have conceived of one or more processes, methods, machines, articles of manufacture, designs, compositions of matter, inventions, discoveries or new or useful improvements relating to METHODS FOR DEPOSITING A MOLYBDENUM METAL FILM OVER A DIELECTRIC SURFACE OF A SUBSTRATE BY A CYCLICAL DEPOSITION PROCESS AND RELATED SEMICONDUCTOR DEVICE STRUCTURES (collectively, the “INVENTIONS”) for which WE have executed and/or may execute one or more patent applications therefore; and

WHEREAS, ASM IP HOLDING B.V. (hereinafter “ASSIGNEE”), a corporation having a place of business at Versterkerstaat 8, Almere, 1322 AP, Netherlands, desires to acquire or otherwise obtain the entire right, title, and interest in and to said INVENTIONS, including all patent applications therefore, and all patents that have granted or may be granted hereafter thereon, including, but not limited to, those identified below.

NOW, THEREFORE, for good and valuable consideration, the receipt of which is hereby acknowledged, WE do hereby acknowledge that WE have sold, assigned, conveyed and transferred, and by these presents do hereby sell, assign, convey and transfer, unto ASSIGNEE, its successors, its legal representatives and its assigns, the entire right, title, and interest throughout the world in and to said INVENTIONS, including all patent applications therefore that may have been filed or may be filed hereafter for said INVENTIONS (including but not limited Application No(s). 16/105,802, filed on August 20, 2018, as Docket No. PAT-AM-0896-US-NP (and do hereby authorize ASSIGNEE and its representative to hereafter add herein such application number(s) and/or filing date(s) when known)) and all rights of priority under International Conventions, Treaties, and Agreements, all utility applications, national phase applications, utility model applications, divisional applications, renewal applications, continuation applications, continuation-in-part applications, patent of addition applications, confirmation applications, validation applications and design applications thereof,

and all issued patents which may have granted or may be granted hereafter thereon and all reissues, renewals, reexaminations, and extensions to any of the foregoing and all patents issuing thereon;

AND WE DO HEREBY authorize and request any Official of any country or countries whose duty it is to issue patents on applications or registrations, to issue all patents for said INVENTIONS to ASSIGNEE, its successors, its legal representatives, and its assigns, in accordance with the terms of this instrument;

AND WE DO HEREBY sell, assign, transfer, and convey to said ASSIGNEE, its successors, its legal representatives, and its assigns all claims for damages and all remedies arising out of or relating to any violation(s) of any of the rights assigned hereby that have or may have accrued prior to the date of assignment to said ASSIGNEE, or may accrue hereafter, including, but not limited to the right to sue for, seek, obtain, collect, recover and retain damages and any ongoing or prospective royalties to which WE may be entitled, or form any settlement or agreement related to any of said patents before or after issuance;

AND WE HEREBY covenant and agree that WE will communicate promptly to said ASSIGNEE, its successors, its legal representatives, and its assigns, any facts known to us respecting said INVENTIONS, and will testify in any legal proceeding, sign all lawful papers, execute all applications and certificates, make all rightful declarations and/or oaths, and provide all lawful assistance to said ASSIGNEE, its successors, its legal representatives, and its assigns, to obtain and enforce patent protection for said INVENTIONS in all countries.

EXECUTED as of the date(s) below by ASSIGNOR:

ZOPE BHUSHAN

Signature

Date

KIRAN SHRESTHA

Signature

Date

SHANKAR SWAMINATHAN

Signature

Date

CHIYU ZHU

Signature

Date

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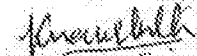
EXECUTED as of the date(s) below by ASSIGNOR:

ZOPE BHUSHAN

Signature

Date

KIRAN SHRESTHA



08-21-2018

Signature

Date

SHANKAR SWAMINATHAN

Signature

Date

CHIYU ZHU

Signature

Date

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EXECUTED as of the date(s) below by ASSIGNOR:

ZOPE BHUSHAN

Signature

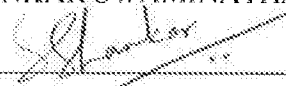
Date

KIRAN SHRESTHA

Signature

Date

SHANKAR SWAMINATHAN



Signature

9/6/2018
Date

CHIYU ZHU

Signature

Date

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EXECUTED as of the date(s) below by ASSIGNOR:

ZOPE BHUSHAN

Signature Date

KIRAN SHRESTHA

Signature Date

SHANKAR SWAMINATHAN

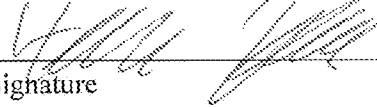
Signature Date

CHIYU ZHU

Chiyu Zhu _____
Signature Date

Oct 21 2020

HENRI TUOMAS ANTERO JUSSILA


Signature

22.8.2018
Date

QI XIE

Signature

Date

HENRI TUOMAS ANTERO JUSSILA

Signature

QI XIE

Qi Xie

Signature

Date

August 21, 2018

Date